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WHAT IS CLAIMED IS:

- A system for dynamically monitoring stability of manufacturing equipment, comprising:
- a process executor requesting a plurality of semimanufactured products processed by the manufacturing equipment to be inspected at a first sampling rate and receiving a plurality of inspection results;
- a data processor analyzing the inspection results from the process executor to determine a second sampling rate;
 - a device storing the second sampling rate; and
- a controller receiving the second sampling rate from the storage device and changing the first sampling rate of the inspection requested by the process executor to the second sampling rate.
- 2. The system as claimed in claim 1 further comprising an input device connected to the storage device for inputting of a third sampling rate, wherein the controller receives the third sampling rate from the storage device and changes the first sampling rate of the inspection of the processed semi-manufactured products guided by the process executor to the third sampling rate.
- 3. The system as claimed in claim 1, further comprising a display connected to the storage device, displaying the first and the second sampling rates.

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- 4. The system as claimed in claim 1 wherein the manufacturing equipment etches the semi-manufactured products.
- 5. The system as claimed in claim 1 wherein the manufacturing equipment forms an oxide layer on the semimanufactured products.
- 6. The system as claimed in claim 1 wherein the process executor is a Manufacturing Executive System.
- 7. The system as claimed in claim 1 wherein the inspection of the semi-manufacturing products is nondestructive.
- 8. The system as claimed in claim 1 wherein one of the semi-manufactured products is a semi-manufactured semiconductor device.
- 9. The system as claimed in claim 8 wherein the semiconductor device is a wafer.
- The system as claimed in claim 1 wherein one of the inspection results is a thickness of an oxide layer.
- The system as claimed in claim 1 wherein one of the inspection results is an etching depth.
- 12. The system as claimed in claim 1 wherein the data processor is an SPC analyzing software application.

Client's ref.:TSMC2000-0278 File: 0503-6062usf/Vincent

1 13. The system as claimed in claim 1 wherein the 2 controller is a server.